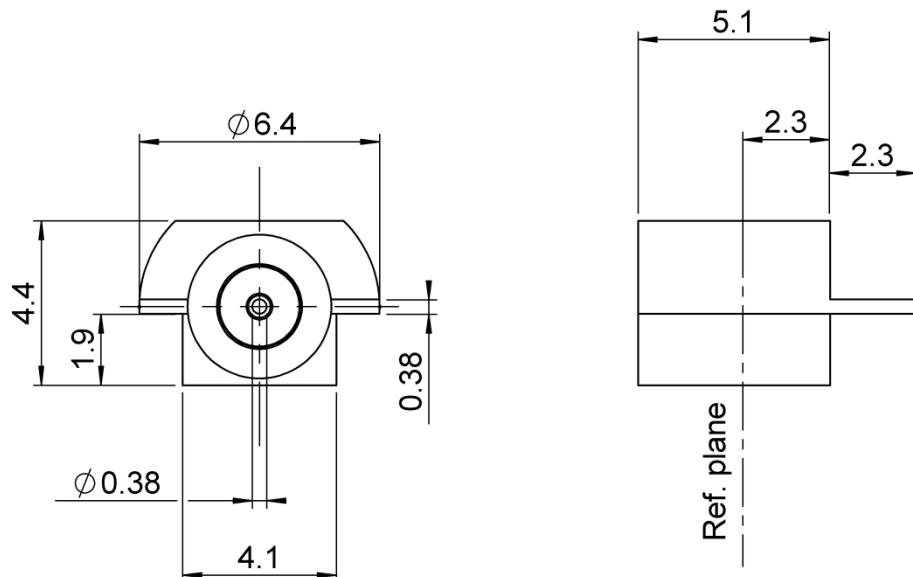


PAGE 1/4

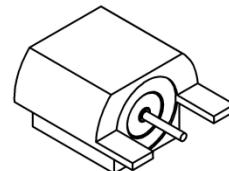
ISSUE
22-12-25A

SERIES **SMP**

PART NUMBER **RS03423000**



Scale: 1/1



All dimensions are in mm. Tolerances according ISO 2768 m-H



COMPONENTS	MATERIALS	PLATING (μm)
Body	BERYLLIUM COPPER	NPGR
Center contact	BERYLLIUM COPPER	N2PGR
Outer contact		
Insulator	PTFE	
Gasket		
Others parts		
-	-	-
-	-	-

PAGE 2/4	ISSUE 22-12-25A	SERIES SMP	PART NUMBER RS03423000
----------	--------------------	-------------------	-------------------------------

PACKAGING

Standard	Unit	Other
1	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance	50	Ω
Frequency	0-12	GHz
VSWR	1.15**	+ 0,000 x F(GHz) Maxi
Insertion loss	0.02+.12**	√F(GHz) dB Maxi
RF leakage	- (NA - F(GHz) dB Maxi
Voltage rating	335	Veff Maxi
Dielectric withstanding voltage	500	Veff mini
Insulation resistance	5000	MΩ mini

ENVIRONMENTAL

Operating temperature	-65/+165	°C
Hermetic seal	NA	Atm.cm ³ /s
Panel leakage	NA	

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	6.8	N mini
Axial force – Opposite end	6.8	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	100	Cycles mini
Nominal Weight (Add +15% for max weight)	0,709	g

SPECIFICATION

RAD-GEN-CONN-006

OTHER CHARACTERISTICS

Assembly instruction:

Others:

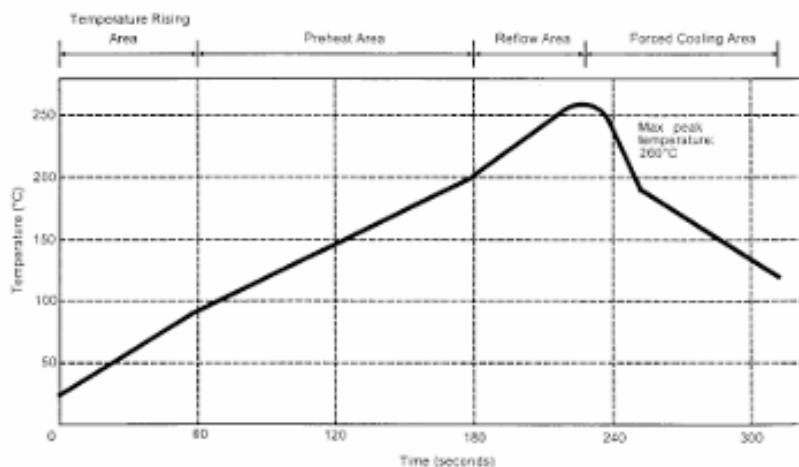
****Coaxial transmission line only**

****Performance strongly depends on layout and PCB material**

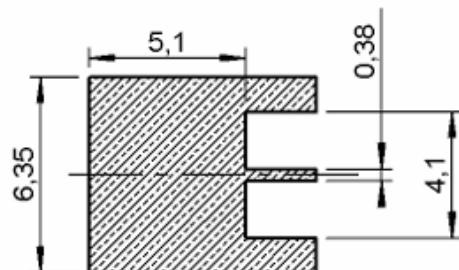
SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microns (.5.9 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow. Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

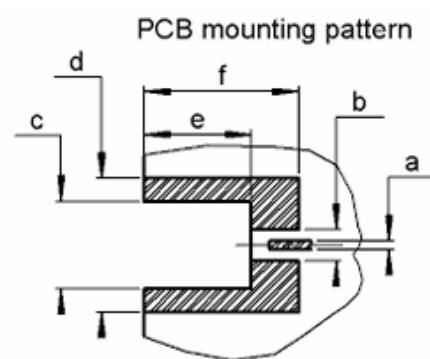
TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec



Shadow of receptacle
for video camera



a	0,48
b	1,5
c	4,18 - 4,32
d	6,5
e	4,95 - 5,45
f	7,52